Vishay Semiconductors

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DPAK (TO-252AA)

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) 51	30
I/C	Anode

PRIMARY CHARACTERISTICS					
I _{F(AV)}	8 A				
V _R	600 V				
V _F at I _F	1.3 V				
t _{rr} (typ.)	18 ns				
T _J max.	175 °C				
Package	DPAK (TO-252AA)				
Circuit configuration	Single				

FEATURES

- Hyper fast recovery time, reduced Q_{rr} and soft recovery
- 175 °C maximum operating junction temperature
- For PFC CRM/CCM operation
- Low forward voltage drop
- Low leakage current
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyper fast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery. The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Peak repetitive reverse voltage	V _{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 143 °C	8				
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	90	А			
Peak repetitive forward current	I _{FM}	$T_{C} = 143 \text{ °C}, f = 20 \text{ kHz}, d = 50 \text{ \%}$	16				
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 $^{\circ}$ C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-	N	
Forward voltage	V _E	I _F = 8 A	-	2.0	2.4	V	
Forward voltage		I _F = 8 A, T _J = 150 °C	-	1.3	1.8		
Poweree leekege ourrept	1	$V_{R} = V_{R}$ rated	-	-	50		
Reverse leakage current	IR	$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	-	500	μA	
Junction capacitance	CT	V _R = 600 V	-	8	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH	

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1

RoHS COMPLIANT

HALOGEN FREE



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DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25$ °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 \text{ A}, \text{ d}I_F/\text{d}t = 50$	0 A/µs, V _R = 30 V		21			
Reverse recovery time	t _{rr}	$I_F = 1 \text{ A}, \text{ d}_F/\text{d}t = 100 \text{ A}/\mu\text{s}, \text{ V}_R = 30 \text{ V}$		-	18	22		
		T _J = 25 °C	I _F = 8 A dI _F /dt = 200 A/μs V _R = 390 V	-	25	-	A nC	
		T _J = 125 °C		-	34	-		
Pools receivers ourrent	I _{RRM}	T _J = 25 °C		-	3.3	-		
Peak recovery current		T _J = 125 °C		-	4.8	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	39	-		
		T _J = 125 °C		-	90	-		

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C	
Thermal resistance, junction to case per leg	R _{thJC}		-	1.8	2.2	°C/W	
Approximate weight				0.3		g	
Approximate weight		0.01 oz		oz.			
Marking device		Case style DPAK (TO-252AA)		8EWH	06FNH		



VS-8EWH06FNHM3

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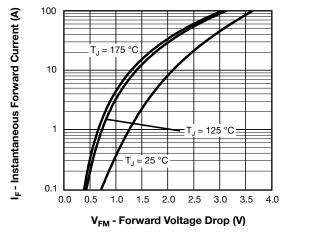


Fig. 1 - Typical Forward Voltage Drop Characteristics

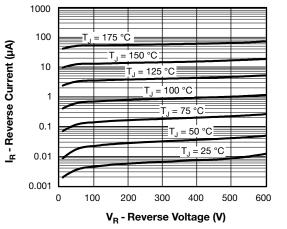


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

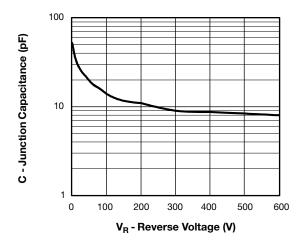
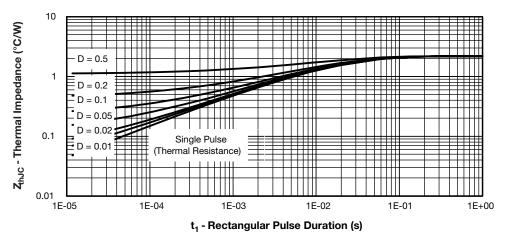


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage





 Revision: 07-Jun-2023
 3
 Document Number: 94739

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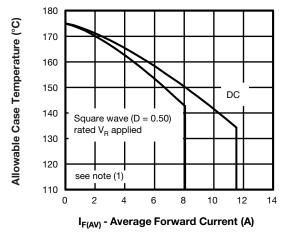


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

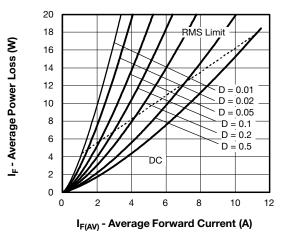


Fig. 6 - Forward Power Loss Characteristics

Note

 $^{(1)}$ Formula used: $T_{C} = T_{J} - (Pd + Pd_{REV}) \times R_{thJC};$ Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}/D$) (see fig. 6); Pd_{REV} = Inverse power loss = $V_{R1} \times I_{R} (1 - D); I_{R}$ at V_{R1} = Rated V_{R}

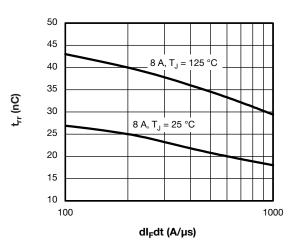


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

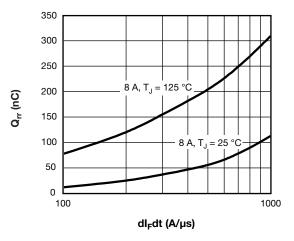


Fig. 8 - Typical Stored Charge vs. dl_F/dt

VS-8EWH06FNHM3

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VS-8EWH06FNHM3



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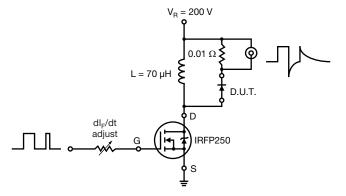


Fig. 9 - Reverse Recovery Parameter Test Circuit

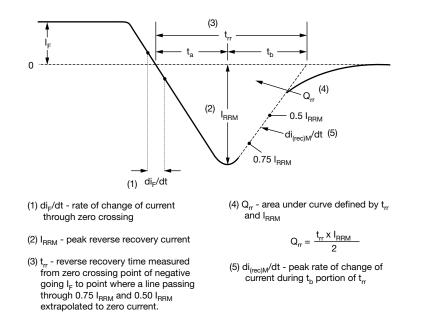


Fig. 10 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

Device code	VS-	8	E	w	н	06	FN	TRL	н	М3
	1	2	3	4	5	6	7	8	9	10
	1 2 3	3 - Circuit configuration:								
	4	- Pa	E = single diode Package identifier: W = D-PAK							
	5 6 7	- Vol	H = hyperfast recovery Voltage rating (06 = 600 V) FN = TO-252AA							
	8	• T	 None = tube TR = tape and reel TRL = tape and reel (left oriented) 							
	9	 TRR = tape and reel (right oriented) H = AEC-Q101 qualified 								
	 Environmental digit: M3 = halogen-free, RoHS-compliant, and terminations lead (F 						ad (Pb)-f			

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-8EWH06FNHM3	75	Antistatic plastic tube					
VS-8EWH06FNTRHM3	2000	13" diameter reel					
VS-8EWH06FNTRRHM3	3000	13" diameter reel					
VS-8EWH06FNTRLHM3	3000	13" diameter reel					

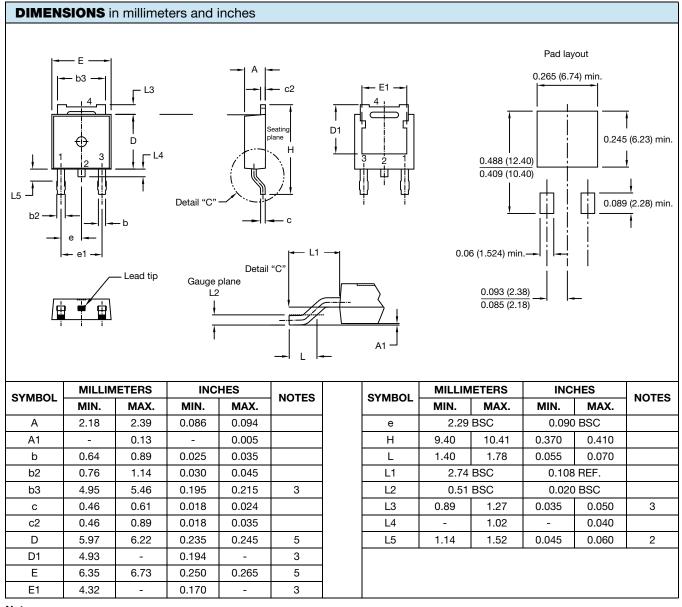
LINKS TO RELATED DOCUMENTS						
Dimensions	www.vishay.com/doc?95519					
Part marking information	www.vishay.com/doc?95518					
Packaging information	www.vishay.com/doc?95033					
SPICE model	www.vishay.com/doc?96114					

Outline Dimensions



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DPAK (TO-252AA)



Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽²⁾ Lead dimension uncontrolled in L5

⁽³⁾ Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁵⁾ Outline conforms to JEDEC[®] outline TO-252AA, except for D1 dimension



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